

NPN Epitaxial Planar Transistor

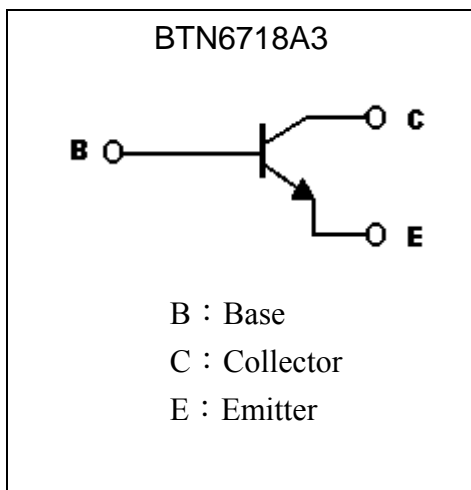
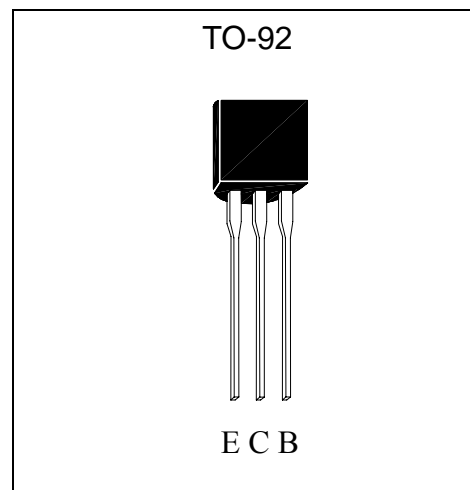
BTN6718A3

Description

The BTN6718A3 is designed for general purpose medium power amplifier and switching applications.

Features

- Low collector saturation voltage
- High breakdown voltage, $V_{CEO}=100V$ (min.)
- High collector current, $I_{C(max)}=1A$ (DC)
- Pb-free package

Symbol

Outline

Absolute Maximum Ratings ($T_a=25^\circ C$)

| Parameter | Symbol | Limits | Unit |
|---|-----------------|----------|--------------|
| Collector-Base Voltage | V_{CBO} | 100 | V |
| Collector-Emitter Voltage | V_{CEO} | 100 | V |
| Emitter-Base Voltage | V_{EBO} | 5 | V |
| Collector Current (DC) | I_C | 1 | A |
| Collector Current (Pulse) | I_{CP} | 2 (Note) | A |
| Power Dissipation | P_D | 850 | mW |
| Thermal Resistance, Junction to Ambient | $R_{\theta JA}$ | 147 | $^\circ C/W$ |
| Junction Temperature | T_j | 150 | $^\circ C$ |
| Storage Temperature | T_{stg} | -55~+150 | $^\circ C$ |

Note : Pulse test, $P_w \leq 10ms$, Duty $\leq 50\%$.

**Characteristics** (Ta=25°C)

| Symbol | Min. | Typ. | Max. | Unit | Test Conditions |
|-----------------------|------|------|------|------|--|
| BV _{CB0} | 100 | - | - | V | I _C =100μA |
| BV _{CEO} | 100 | - | - | V | I _C =1mA |
| BV _{EBO} | 5 | - | - | V | I _E =10μA |
| I _{CB0} | - | - | 100 | nA | V _{CB} =80V, I _E =0 |
| I _{EBO} | - | - | 100 | nA | V _{EB} =4V, I _C =0 |
| *V _{CE(SAT)} | - | - | 350 | mV | I _C =350mA, I _B =35mA |
| *h _{FE 1} | 90 | - | - | - | V _{CE} =1V, I _C =50mA |
| *h _{FE 2} | 100 | - | 300 | - | V _{CE} =1V, I _C =250mA |
| *h _{FE 3} | 20 | - | - | - | V _{CE} =1V, I _C =500mA |
| f _T | 50 | - | - | MHz | V _{CE} =10V, I _C =50mA, f=100MHz |
| C _{ob} | - | - | 20 | pF | V _{CB} =10V, I _E =0A, f=1MHz |

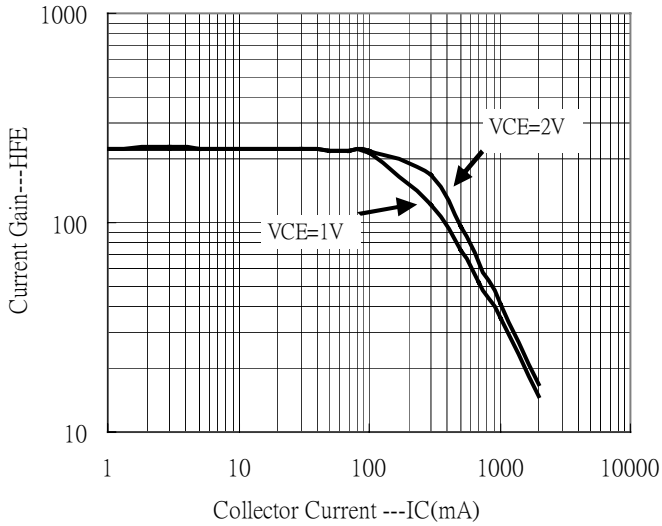
*Pulse Test: Pulse Width ≤380μs, Duty Cycle≤2%

Ordering Information

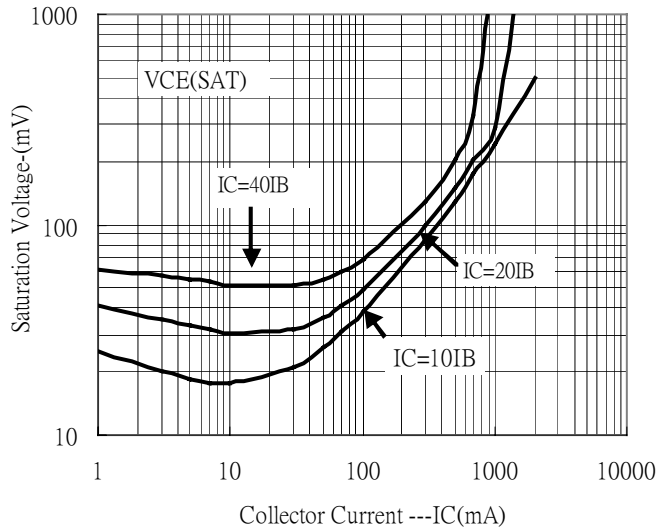
| Device | Package | Shipping | Marking |
|-----------|--------------------|-----------------------|---------|
| BTN6718A3 | TO-92 (Pb-free) | 2000 pcs / Tape & Box | N6718 |

Characteristic Curves

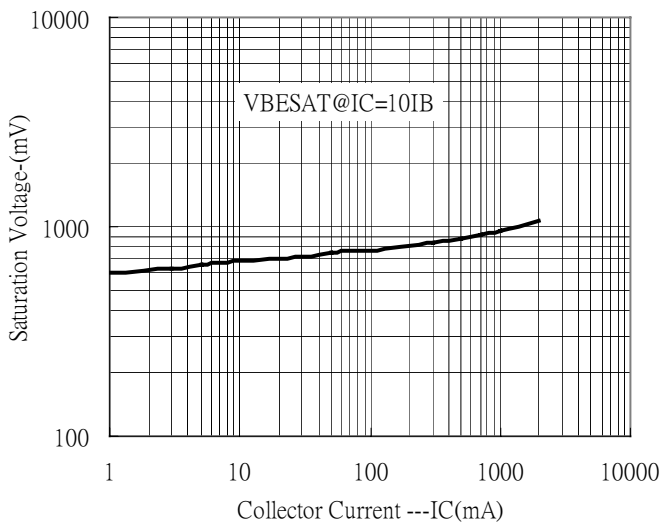
Current Gain vs Collector Current



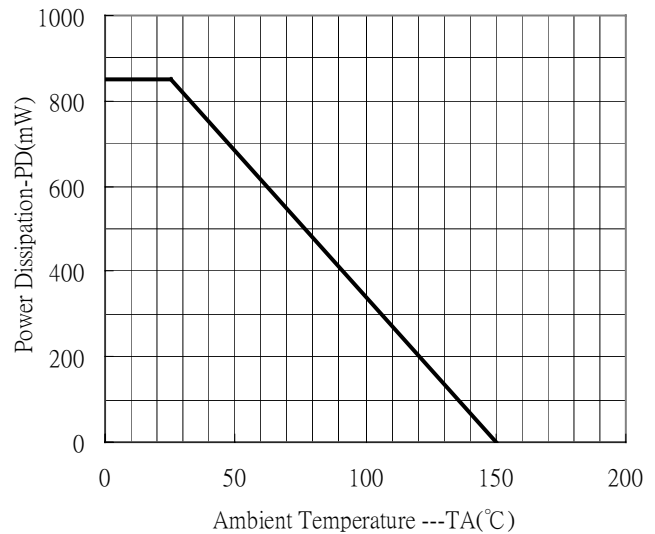
Saturation Voltage vs Collector Current



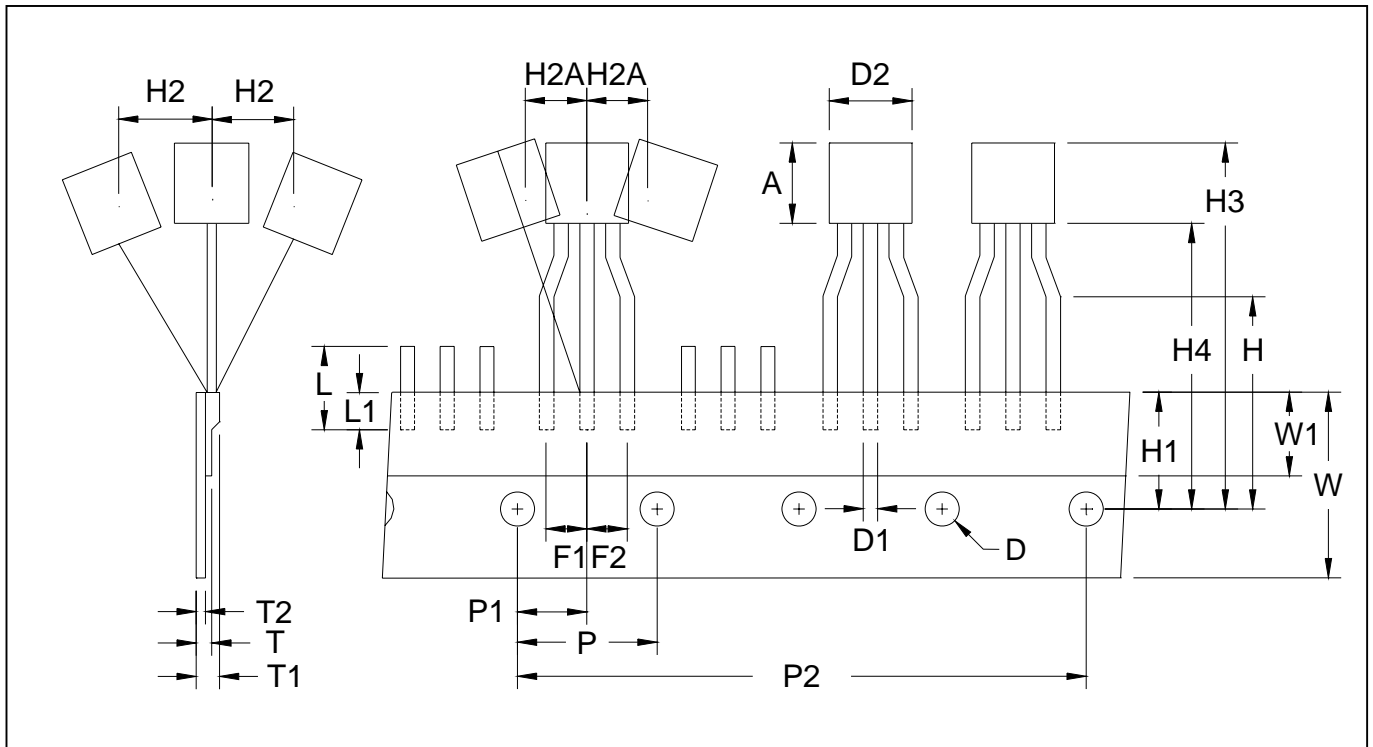
Saturation Voltage vs Collector Current



Power Derating Curve

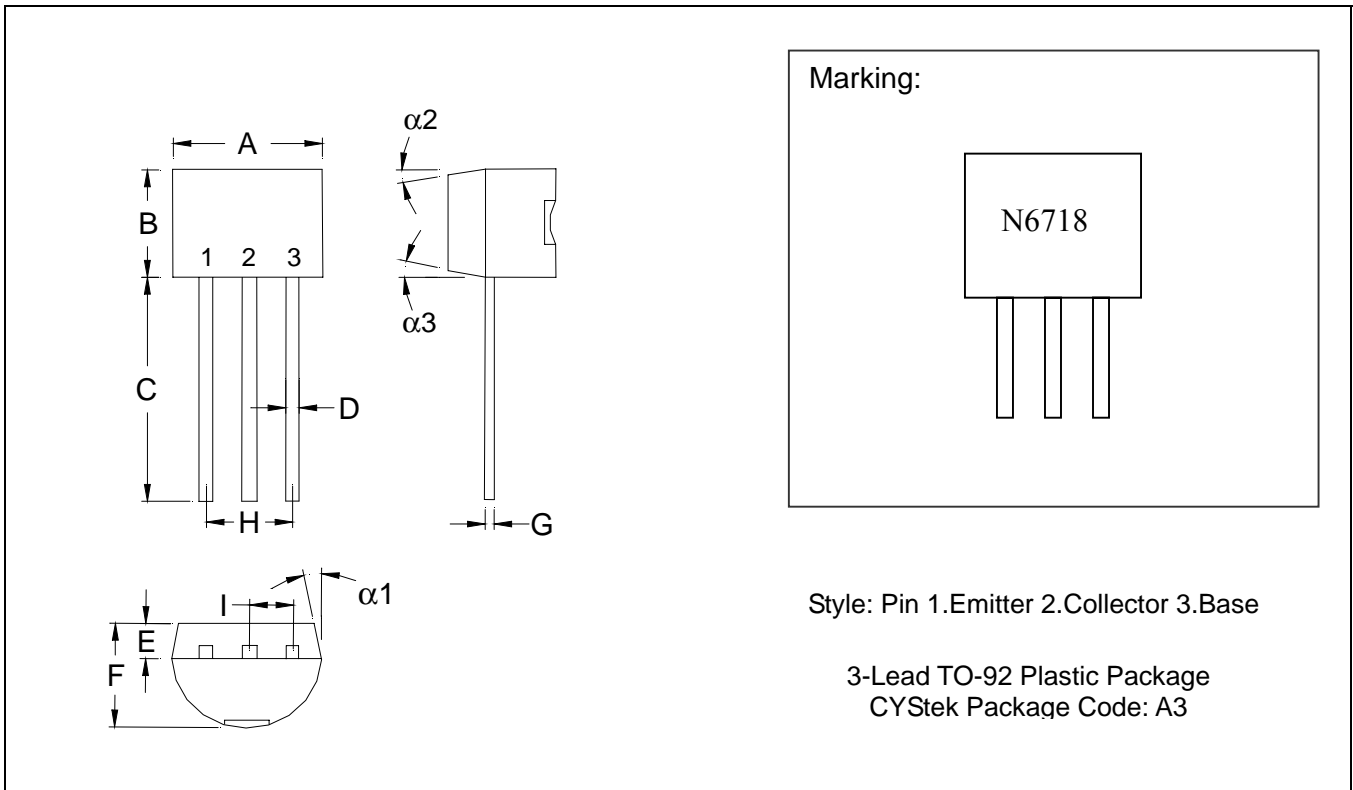


TO-92 Taping Outline



| DIM | Item | Millimeters | |
|-------|-------------------------------------|-------------|-------|
| | | Min. | Max. |
| A | Component body height | 4.33 | 4.83 |
| D | Tape Feed Diameter | 3.80 | 4.20 |
| D1 | Lead Diameter | 0.36 | 0.53 |
| D2 | Component Body Diameter | 4.33 | 4.83 |
| F1,F2 | Component Lead Pitch | 2.40 | 2.90 |
| F1,F2 | F1-F2 | - | ±0.3 |
| H | Height Of Seating Plane | 15.50 | 16.50 |
| H1 | Feed Hole Location | 8.50 | 9.50 |
| H2 | Front To Rear Deflection | - | 1 |
| H2A | Deflection Left Or Right | - | 1 |
| H3 | Component Height | - | 27 |
| H4 | Feed Hole To Bottom Of Component | - | 21 |
| L | Lead Length After Component Removal | - | 11 |
| L1 | Lead Wire Enclosure | 2.50 | - |
| P | Feed Hole Pitch | 12.50 | 12.90 |
| P1 | Center Of Seating Plane Location | 5.95 | 6.75 |
| P2 | 4 Feed Hole Pitch | 50.30 | 51.30 |
| T | Over All Tape Thickness | - | 0.55 |
| T1 | Total Taped Package Thickness | - | 1.42 |
| T2 | Carrier Tape Thickness | 0.36 | 0.68 |
| W | Tape Width | 17.50 | 19.00 |
| W1 | Adhesive Tape Width | 5.00 | 7.00 |
| - | 20 pcs Pitch | 253 | 255 |

TO-92 Dimension



*: Typical

| DIM | Inches | | Millimeters | | DIM | Inches | | Millimeters | |
|-----|--------|---------|-------------|-------|------------|--------|---------|-------------|-------|
| | Min. | Max. | Min. | Max. | | Min. | Max. | Min. | Max. |
| A | 0.1704 | 0.1902 | 4.33 | 4.83 | G | 0.0142 | 0.0220 | 0.36 | 0.56 |
| B | 0.1704 | 0.1902 | 4.33 | 4.83 | H | - | *0.1000 | - | *2.54 |
| C | 0.5000 | - | 12.70 | - | I | - | *0.0500 | - | *1.27 |
| D | 0.0142 | 0.0220 | 0.36 | 0.56 | $\alpha 1$ | - | *5° | - | *5° |
| E | - | *0.0500 | - | *1.27 | $\alpha 2$ | - | *2° | - | *2° |
| F | 0.1323 | 0.1480 | 3.36 | 3.76 | $\alpha 3$ | - | *2° | - | *2° |

Notes: 1. Controlling dimension: millimeters.
 2. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3. If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: 42 Alloy ; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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